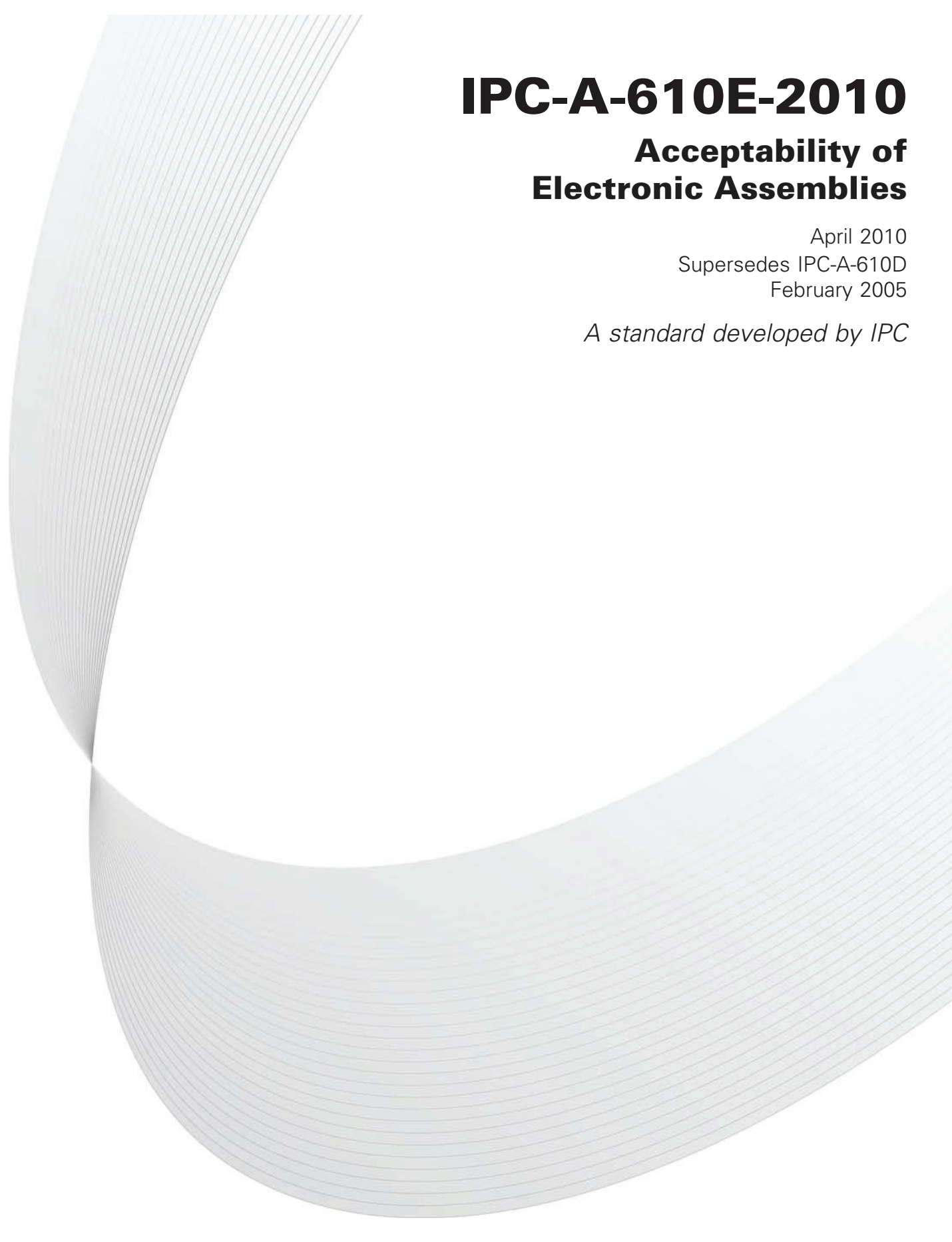




IPC-A-610E-2010

Acceptability of Electronic Assemblies

April 2010
Supersedes IPC-A-610D
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A standard developed by IPC

Association Connecting Electronics Industries



Table of Contents

1 Foreword	1-1	2 Applicable Documents	2-1
1.1 Scope	1-2	2.1 IPC Documents	2-1
1.2 Purpose	1-3	2.2 Joint Industry Documents	2-1
1.3 Classification	1-3	2.3 EOS/ESD Association Documents	2-2
1.4 Definition of Requirements	1-3	2.4 Electronics Industries Alliance Documents	2-2
1.4.1 Acceptance Criteria	1-3	2.5 International Electrotechnical Commission Documents	2-2
1.4.1.1 Target Condition	1-3	2.6 ASTM	2-2
1.4.1.2 Acceptable Condition	1-4	2.7 Technical Publications	2-2
1.4.1.3 Defect Condition	1-4	3 Handling Electronic Assemblies	3-1
1.4.1.3.1 Disposition	1-4	3.1 EOS/ESD Prevention	3-2
1.4.1.4 Process Indicator Condition	1-4	3.1.1 Electrical Overstress (EOS)	3-3
1.4.1.4.1 Process Indicator Methodologies	1-4	3.1.2 Electrostatic Discharge (ESD)	3-4
1.4.1.5 Combined Conditions	1-4	3.1.3 Warning Labels	3-5
1.4.1.6 Conditions Not Specified	1-4	3.1.4 Protective Materials	3-6
1.4.1.7 Specialized Designs	1-4	3.2 EOS/ESD Safe Workstation/EPA	3-7
1.5 Terms & Definitions	1-4	3.3 Handling Considerations	3-9
1.5.1 Board Orientation	1-4	3.3.1 Guidelines	3-9
1.5.1.1 *Primary Side	1-5	3.3.2 Physical Damage	3-10
1.5.1.2 *Secondary Side	1-5	3.3.3 Contamination	3-10
1.5.1.3 Solder Source Side	1-5	3.3.4 Electronic Assemblies	3-10
1.5.1.4 Solder Destination Side	1-5	3.3.5 After Soldering	3-11
1.5.2 *Cold Solder Connection	1-5	3.3.6 Gloves and Finger Cots	3-12
1.5.3 Electrical Clearance	1-5	4 Hardware	4-1
1.5.4 High Voltage	1-5	4.1 Hardware Installation	4-2
1.5.5 Intrusive Solder	1-5	4.1.1 Electrical Clearance	4-2
1.5.6 *Leaching	1-5	4.1.2 Interference	4-3
1.5.7 Meniscus (Component)	1-5	4.1.3 Heatsinks	4-3
1.5.8 *Nonfunctional Land	1-5	4.1.3.1 Insulators and Thermal Compounds	4-3
1.5.9 Pin-in-Paste	1-5	4.1.3.2 Contact	4-5
1.5.10 Wire Diameter	1-5	4.1.4 Threaded Fasteners	4-6
1.5.11 Wire Overwrap	1-5	4.1.4.1 Torque	4-8
1.5.12 Wire Overlap	1-5	4.1.4.2 Wires	4-9
1.6 Examples and Illustrations	1-5	4.2 Jackpost Mounting	4-11
1.7 Inspection Methodology	1-5		
1.8 Verification of Dimensions	1-6		
1.9 Magnification Aids	1-6		
1.10 Lighting	1-6		

Table of Contents (cont.)

4.3 Connector Pins	4-12	6.1.3 Flared Flange	6-6
4.3.1 Edge Connector Pins	4-12	6.1.4 Controlled Split	6-7
4.3.2 Press Fit Pins	4-14	6.1.5 Solder	6-8
4.3.2.1 Soldering	4-16		
4.4 Wire Bundle Securing	4-19	6.2 Insulation	6-10
4.4.1 General	4-19	6.2.1 Damage	6-10
4.4.2 Lacing	4-22	6.2.1.1 Presolder	6-10
4.4.2.1 Lacing – Damage	4-23	6.2.1.2 Post-Solder	6-12
4.5 Routing	4-24	6.2.2 Clearance	6-13
4.5.1 Wire Crossover	4-24	6.2.3 Flexible Sleeve	6-15
4.5.2 Bend Radius	4-25	6.2.3.1 Placement	6-15
4.5.3 Coaxial Cable	4-26	6.2.3.2 Damage	6-17
4.5.4 Unused Wire Termination	4-27		
4.5.5 Ties over Splices and Ferrules	4-28	6.3 Conductor	6-18
5 Soldering	5-1	6.3.1 Deformation	6-18
5.1 Soldering Acceptability Requirements	5-3	6.3.2 Strand Damage	6-19
5.2 Soldering Anomalies	5-4	6.3.3 Strand Separation (Birdcaging) – Presolder	6-20
5.2.1 Exposed Basis Metal	5-4	6.3.4 Strand Separation (Birdcaging) – Post-Solder	6-21
5.2.2 Pin Holes/Blow Holes	5-6	6.3.5 Tinning	6-22
5.2.3 Reflow of Solder Paste	5-7		
5.2.4 Nonwetting	5-8	6.4 Service Loops	6-24
5.2.5 Cold/Rosin Connection	5-9	6.5 Terminals – Stress Relief	6-25
5.2.6 Dewetting	5-9	6.5.1 Bundle	6-25
5.2.7 Excess Solder	5-10	6.5.2 Lead/Wire Bend	6-26
5.2.7.1 Solder Balls/Solder Fines	5-10		
5.2.7.2 Bridging	5-12	6.6 Terminals – Lead/Wire Placement – General Requirements	6-28
5.2.7.3 Solder Webbing/Splashes	5-13		
5.2.8 Disturbed Solder	5-14	6.7 Terminals – Solder – General Requirements ...	6-30
5.2.9 Fractured Solder	5-15	6.8 Terminals – Turrets and Straight Pins	6-31
5.2.10 Solder Projections	5-16	6.8.1 Lead/Wire Placement	6-31
5.2.11 Lead Free Fillet Lift	5-17	6.8.2 Solder	6-33
5.2.12 Lead Free Hot Tear/Shrink Hole	5-18		
5.2.13 Probe Marks and Other Similar Surface Conditions in Solder Joints	5-19	6.9 Terminals – Bifurcated	6-34
6 Terminal Connections	6-1	6.9.1 Lead/Wire Placement – Side Route Attachments	6-34
6.1 Swaged Hardware	6-2	6.9.2 Lead/Wire Placement – Bottom and Top Route Attachments	6-37
6.1.1 Terminals	6-2	6.9.3 Lead/Wire Placement – Staked Wires	6-38
6.1.1.1 Terminal Base – Pad Gap	6-2	6.9.4 Solder	6-39
6.1.1.2 Terminals – Turret	6-3		
6.1.1.3 Terminals – Bifurcated	6-4	6.10 Terminals – Slotted	6-42
6.1.2 Rolled Flange	6-5	6.10.1 Lead/Wire Placement	6-42
		6.10.2 Solder	6-43

Table of Contents (cont.)

6.11 Terminals – Pierced/Perforated	6-44	7.2 Component Securing	7-25
6.11.1 Lead/Wire Placement	6-44	7.2.1 Mounting Clips	7-25
6.11.2 Solder	6-46	7.2.2 Adhesive Bonding	7-27
6.12 Terminals – Hook	6-47	7.2.2.1 Adhesive Bonding – Nonelevated Components	7-28
6.12.1 Lead/Wire Placement	6-47	7.2.2.2 Adhesive Bonding – Elevated Components	7-31
6.12.2 Solder	6-49	7.2.3 Wire Hold Down	7-32
6.13 Terminals – Solder Cups	6-50	7.3 Supported Holes	7-33
6.13.1 Lead/Wire Placement	6-50	7.3.1 Axial Leaded – Horizontal	7-33
6.13.2 Solder	6-52	7.3.2 Axial Leaded – Vertical	7-35
6.14 Terminals – AWG 30 and Smaller Diameter Wires	6-54	7.3.3 Wire/Lead Protrusion	7-37
6.14.1 Lead/Wire Placement	6-54	7.3.4 Wire/Lead Clinches	7-38
6.15 Terminals – Series Connected	6-55	7.3.5 Solder	7-40
6.16 Terminals – Edge Clip – Position	6-56	7.3.5.1 Vertical fill (A)	7-43
7 Through Hole Technology	7-1	7.3.5.2 Primary Side – Lead to Barrel (B)	7-45
7.1 Component Mounting	7-2	7.3.5.3 Primary Side – Land Area Coverage (C)	7-47
7.1.1 Orientation	7-2	7.3.5.4 Secondary Side – Lead to Barrel (D)	7-48
7.1.1.1 Horizontal	7-3	7.3.5.5 Secondary Side – Land Area Coverage (E)	7-49
7.1.1.2 Vertical	7-5	7.3.5.6 Solder Conditions – Solder in Lead Bend	7-50
7.1.2 Lead Forming	7-6	7.3.5.7 Solder Conditions – Touching Through-Hole Component Body	7-51
7.1.2.1 Bends	7-6	7.3.5.8 Solder Conditions – Meniscus in Solder	7-52
7.1.2.2 Stress Relief	7-8	7.3.5.9 Lead Cutting after Soldering	7-53
7.1.2.3 Damage	7-10	7.3.5.10 Coated Wire Insulation in Solder	7-54
7.1.3 Leads Crossing Conductors	7-11	7.3.5.11 Interfacial Connection without Lead – Vias	7-55
7.1.4 Hole Obstruction	7-12	7.3.5.12 Board in Board	7-56
7.1.5 DIP/SIP Devices and Sockets	7-13	7.4 Unsupported Holes	7-59
7.1.6 Radial Leads – Vertical	7-15	7.4.1 Axial Leads – Horizontal	7-59
7.1.6.1 Spacers	7-16	7.4.2 Axial Leads – Vertical	7-60
7.1.7 Radial Leads – Horizontal	7-18	7.4.3 Wire/Lead Protrusion	7-61
7.1.8 Connectors	7-19	7.4.4 Wire/Lead Clinches	7-62
7.1.8.1 Right Angle	7-21	7.4.5 Solder	7-64
7.1.8.2 Vertical Shrouded Pin Headers and Vertical Receptacle Connectors	7-22	7.4.6 Lead Cutting after Soldering	7-66
7.1.9 High Power	7-23	7.5 Jumper Wires	7-67
7.1.10 Conductive Cases	7-24	7.5.1 Wire Selection	7-67
		7.5.2 Wire Routing	7-68
		7.5.3 Wire Staking	7-70
		7.5.4 Supported Holes	7-72
		7.5.4.1 Lead in Hole	7-72
		7.5.5 Wrapped Attachment	7-73
		7.5.6 Lap Soldered	7-73

Table of Contents (cont.)

8 Surface Mount Assemblies	8-1	8.3.3.3 End Joint Width (C)	8-36
8.1 Staking Adhesive	8-3	8.3.3.4 Side Joint Length (D)	8-37
8.1.1 Component Bonding	8-3	8.3.3.5 Maximum Fillet Height (E)	8-38
8.1.2 Mechanical Strength	8-4	8.3.3.6 Minimum Fillet Height (F)	8-39
8.2 SMT Leads	8-7	8.3.3.7 Solder Thickness (G)	8-40
8.2.1 Damage	8-7	8.3.3.8 End Overlap (J)	8-41
8.2.2 Flattening	8-7	8.3.4 Castellated Terminations	8-42
8.3 SMT Connections	8-8	8.3.4.1 Side Overhang (A)	8-43
8.3.1 Chip Components – Bottom Only Terminations	8-8	8.3.4.2 End Overhang (B)	8-44
8.3.1.1 Side Overhang (A)	8-9	8.3.4.3 Minimum End Joint Width (C)	8-44
8.3.1.2 End Overhang (B)	8-10	8.3.4.4 Minimum Side Joint Length (D)	8-45
8.3.1.3 End Joint Width (C)	8-11	8.3.4.5 Maximum Fillet Height (E)	8-45
8.3.1.4 Side Joint Length (D)	8-12	8.3.4.6 Minimum Fillet Height (F)	8-46
8.3.1.5 Maximum Fillet Height (E)	8-13	8.3.4.7 Solder Thickness (G)	8-46
8.3.1.6 Minimum Fillet Height (F)	8-13	8.3.5 Flat Gull Wing Leads	8-47
8.3.1.7 Solder Thickness (G)	8-14	8.3.5.1 Side Overhang (A)	8-47
8.3.1.8 End Overlap (J)	8-14	8.3.5.2 Toe Overhang (B)	8-51
8.3.2 Rectangular or Square End Chip Components – 1, 3 or 5 Side Terminations	8-15	8.3.5.3 Minimum End Joint Width (C)	8-52
8.3.2.1 Side Overhang (A)	8-16	8.3.5.4 Minimum Side Joint Length (D)	8-54
8.3.2.2 End Overhang (B)	8-18	8.3.5.5 Maximum Heel Fillet Height (E)	8-56
8.3.2.3 End Joint Width (C)	8-19	8.3.5.6 Minimum Heel Fillet Height (F)	8-57
8.3.2.4 Side Joint Length (D)	8-21	8.3.5.7 Solder Thickness (G)	8-58
8.3.2.5 Maximum Fillet Height (E)	8-22	8.3.5.8 Coplanarity	8-59
8.3.2.6 Minimum Fillet Height (F)	8-23	8.3.6 Round or Flattened (Coined) Gull Wing Leads	8-60
8.3.2.7 Solder Thickness (G)	8-24	8.3.6.1 Side Overhang (A)	8-61
8.3.2.8 End Overlap (J)	8-25	8.3.6.2 Toe Overhang (B)	8-62
8.3.2.9 Termination Variations	8-26	8.3.6.3 Minimum End Joint Width (C)	8-62
8.3.2.9.1 Mounting on Side (Billboarding)	8-26	8.3.6.4 Minimum Side Joint Length (D)	8-63
8.3.2.9.2 Mounting Upside Down	8-28	8.3.6.5 Maximum Heel Fillet Height (E)	8-64
8.3.2.9.3 Stacking	8-29	8.3.6.6 Minimum Heel Fillet Height (F)	8-65
8.3.2.9.4 Tombstoning	8-30	8.3.6.7 Solder Thickness (G)	8-66
8.3.2.10 3 Terminations	8-31	8.3.6.8 Minimum Side Joint Height (Q)	8-66
8.3.2.10.1 3 Terminations – Solder Width	8-31	8.3.6.9 Coplanarity	8-67
8.3.2.10.2 3 Terminations – Minimum Fillet Height	8-32	8.3.7 J Leads	8-68
8.3.3 Cylindrical End Cap Terminations	8-33	8.3.7.1 Side Overhang (A)	8-68
8.3.3.1 Side Overhang (A)	8-34	8.3.7.2 Toe Overhang (B)	8-70
8.3.3.2 End Overhang (B)	8-35	8.3.7.3 End Joint Width (C)	8-70
		8.3.7.4 Side Joint Length (D)	8-72
		8.3.7.5 Maximum Heel Fillet Height (E)	8-73
		8.3.7.6 Minimum Heel Fillet Height (F)	8-74
		8.3.7.7 Solder Thickness (G)	8-76
		8.3.7.8 Coplanarity	8-76

Table of Contents (cont.)

8.3.8 Butt/I Connections	8-77	8.5 Surface Mount Connectors	8-99
8.3.8.1 Maximum Side Overhang (A)	8-77	8.6 Jumper Wires	8-100
8.3.8.2 Maximum Toe Overhang (B)	8-78	8.6.1 SMT	8-101
8.3.8.3 Minimum End Joint Width (C)	8-78	8.6.1.1 Chip and Cylindrical End Cap Components ..	8-101
8.3.8.4 Minimum Side Joint Length (D)	8-79	8.6.1.2 Gull Wing	8-102
8.3.8.5 Maximum Fillet Height (E)	8-79	8.6.1.3 J Lead	8-103
8.3.8.6 Minimum Fillet Height (F)	8-80	8.6.1.4 Castellations	8-103
8.3.8.7 Solder Thickness (G)	8-80	8.6.1.5 Land	8-104
8.3.9 Flat Lug Leads	8-81	9 Component Damage	9-1
8.3.10 Tall Profile Components Having Bottom Only Terminations	8-82	9.1 Loss of Metallization	9-2
8.3.11 Inward Formed L-Shaped Ribbon Leads	8-83	9.2 Chip Resistor Element	9-3
8.3.12 Surface Mount Area Array	8-85	9.3 Leaded/Leadless Devices	9-4
8.3.12.1 Alignment	8-86	9.4 Ceramic Chip Capacitors	9-8
8.3.12.2 Solder Ball Spacing	8-86	9.5 Connectors	9-10
8.3.12.3 Solder Connections	8-87	9.6 Relays	9-13
8.3.12.4 Voids	8-89	9.7 Transformer Core Damage	9-13
8.3.12.5 Underfill/Staking	8-89	9.8 Connectors, Handles, Extractors, Latches	9-14
8.3.12.6 Package on Package	8-90	9.9 Edge Connector Pins	9-15
8.3.13 Bottom Termination Components (BTC)	8-92	9.10 Press Fit Pins	9-16
8.3.14 Components with Bottom Thermal Plane Terminations	8-94	9.11 Backplane Connector Pins	9-17
8.3.15 Flattened Post Connections	8-96	9.12 Heat Sink Hardware	9-12
8.3.15.1 Maximum Termination Overhang – Square Solder Land	8-96		
8.3.15.2 Maximum Termination Overhang – Round Solder Land	8-97		
8.3.15.3 Maximum Fillet Height	8-97		
8.4 Specialized SMT Terminations	8-98		

Table of Contents (cont.)

10 Printed Circuit Boards and Assemblies	10-1	10.6.3 Chlorides, Carbonates and White Residues	10-40
10.1 Gold Surface Contact Area	10-2	10.6.4 Flux Residues – No-Clean Process – Appearance	10-42
10.2 Laminate Conditions	10-4	10.6.5 Surface Appearance	10-43
10.2.1 Measling and Crazeing	10-5	10.7 Solder Mask Coating	10-44
10.2.2 Blistering and Delamination	10-7	10.7.1 Wrinkling/Cracking	10-45
10.2.3 Weave Texture/Weave Exposure	10-9	10.7.2 Voids, Blisters, Scratches	10-47
10.2.4 Haloing and Edge Delamination	10-10	10.7.3 Breakdown	10-48
10.2.5 Burns	10-12	10.7.4 Discoloration	10-49
10.2.6 Bow and Twist	10-13	10.8 Conformal Coating	10-49
10.2.7 Depanelization	10-14	10.8.1 General	10-49
10.3 Conductors/Lands	10-16	10.8.2 Coverage	10-50
10.3.1 Reduction in Cross-Sectional Area	10-16	10.8.3 Thickness	10-52
10.3.2 Lifted Pads/Lands	10-17	10.9 Encapsulation	10-53
10.3.3 Mechanical Damage	10-19	11 Discrete Wiring	11-1
10.4 Flexible and Rigid-Flex Printed Circuitry	10-20	11.1 Solderless Wrap	11-2
10.4.1 Damage	10-20	11.1.1 Number of Turns	11-3
10.4.2 Delamination	10-22	11.1.2 Turn Spacing	11-4
10.4.3 Discoloration	10-23	11.1.3 End Tails, Insulation Wrap	11-5
10.4.4 Solder Wicking	10-24	11.1.4 Raised Turns Overlap	11-7
10.4.5 Attachment	10-25	11.1.5 Connection Position	11-8
10.5 Marking	10-26	11.1.6 Wire Dress	11-10
10.5.1 Etched (Including Hand Printing)	10-28	11.1.7 Wire Slack	11-11
10.5.2 Screened	10-29	11.1.8 Wire Plating	11-12
10.5.3 Stamped	10-31	11.1.9 Damaged Insulation	11-13
10.5.4 Laser	10-32	11.1.10 Damaged Conductors & Terminals	11-14
10.5.5 Labels	10-34	11.2 Component Mounting – Connector Wire Dress Strain/Stress Relief	11-15
10.5.5.1 Bar Coding	10-34	12 High Voltage	12-1
10.5.5.2 Readability	10-34	Appendix A Electrical Conductor Spacing	A-1
10.5.5.3 Adhesion and Damage	10-35	Index	Index-1
10.5.5.4 Position	10-35		
10.5.6 Using Radio Frequency Identification (RFID) Tags	10-36		
10.6 Cleanliness	10-37		
10.6.1 Flux Residues	10-38		
10.6.2 Particulate Matter	10-39		

1 Acceptability of Electronic Assemblies

Foreword

The following topics are addressed in this section:

1.1 Scope

1.2 Purpose

1.3 Classification

1.4 Definition of Requirements

- 1.4.1 Acceptance Criteria
 - 1.4.1.1 Target Condition
 - 1.4.1.2 Acceptable Condition
 - 1.4.1.3 Defect Condition
 - 1.4.1.3.1 Disposition
 - 1.4.1.4 Process Indicator Condition
 - 1.4.1.4.1 Process Indicator Methodologies
 - 1.4.1.5 Combined Conditions
 - 1.4.1.6 Conditions Not Specified
 - 1.4.1.7 Specialized Designs

1.5 Terms & Definitions

- 1.5.1 Board Orientation
 - 1.5.1.1 *Primary Side

- 1.5.1.2 *Secondary Side
- 1.5.1.3 Solder Source Side
- 1.5.1.4 Solder Destination Side
- 1.5.2 *Cold Solder Connection
- 1.5.3 Electrical Clearance
- 1.5.4 High Voltage
- 1.5.5 Intrusive Solder
- 1.5.6 *Leaching
- 1.5.7 Meniscus (Component)
- 1.5.8 *Nonfunctional Land
- 1.5.9 Pin-in-Paste
- 1.5.10 Wire Diameter
- 1.5.11 Wire Overwrap
- 1.5.12 Wire Overlap

1.6 Examples and Illustrations

1.7 Inspection Methodology

1.8 Verification of Dimensions

1.9 Magnification Aids

1.10 Lighting